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Title: priconductor Package with Integrated Heat Spier Attached to a Therma Inductive Substrate Core

Thermal inductive Substration Time

Timothy M. Takeuchi

Atty. Docket No.:

42390P13557

100

FABRICATE A PACKAGE SUBSTRATE HAVING TOP AND BOTTOM SURFACE BUILDUP LAYERS DISPOSED ON A THERMALLY CONDUCTIVE SUBSTRATE CORE

102

EXPOSE A PORTION OF THE SUBSTRATE CORE AT A TOP SURFACE OF THE PACKAGE SUBSTRATE TO ALLOW FOR ATTACHMENT OF A HEAT SPREADER

104

MOUNT AN INTEGRATED CIRCUIT TO THE TOP SURFACE OF THE PACKAGE SUBSTRATE WITH A TOP SURFACE OF THE INTEGRATED CIRCUIT FACING DOWN

106

ATTACH A HEAT SPREADER TO THE PACKAGE SUBSTRATE,
THE HEAT SPREADER THERMALLY COUPLED TO THE
EXPOSED PORTION OF THE SUBSTRATE CORE AND TO A
BACKSIDE SURFACE OF THE INTEGRATED CIRCUIT

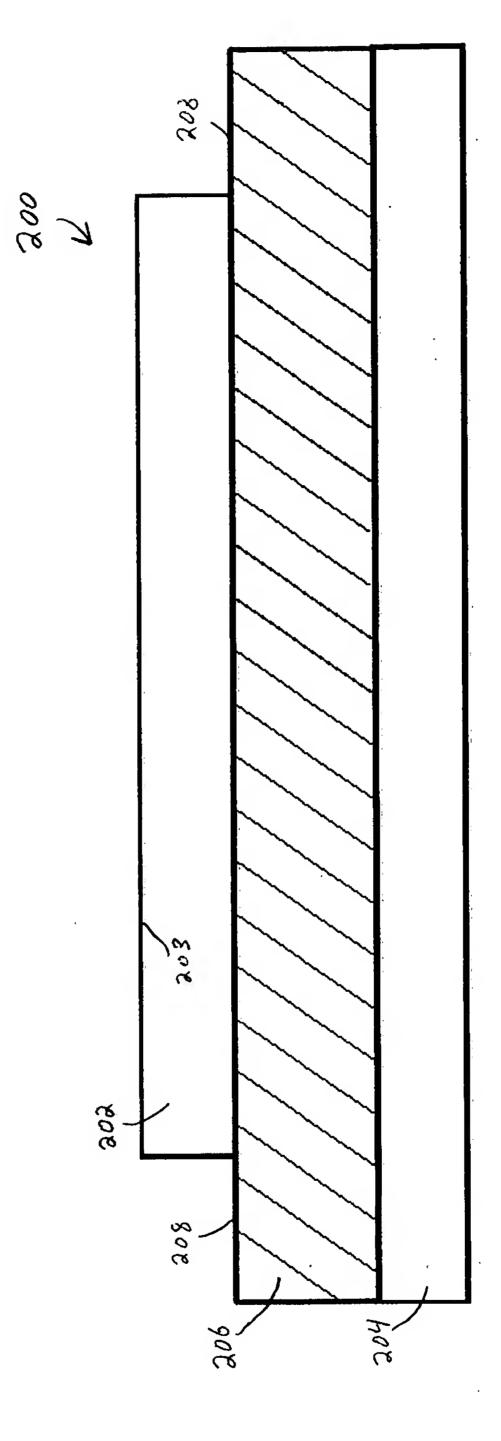
108

Figure 1

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Title: Semiconductor Package with Integrated Heat Spreader Attached to a Thermally Conductive Substrate Core Inventor(s): Timothy M. Takeuchi

Inventor(s): Atty. Docket No.: 42390P13557



Semiconductor Package with Integrated Heat Spreader Attached to a :əltiT

Timothy M. Takeuchi 42390P13557 Thermally Conductive Substrate Core

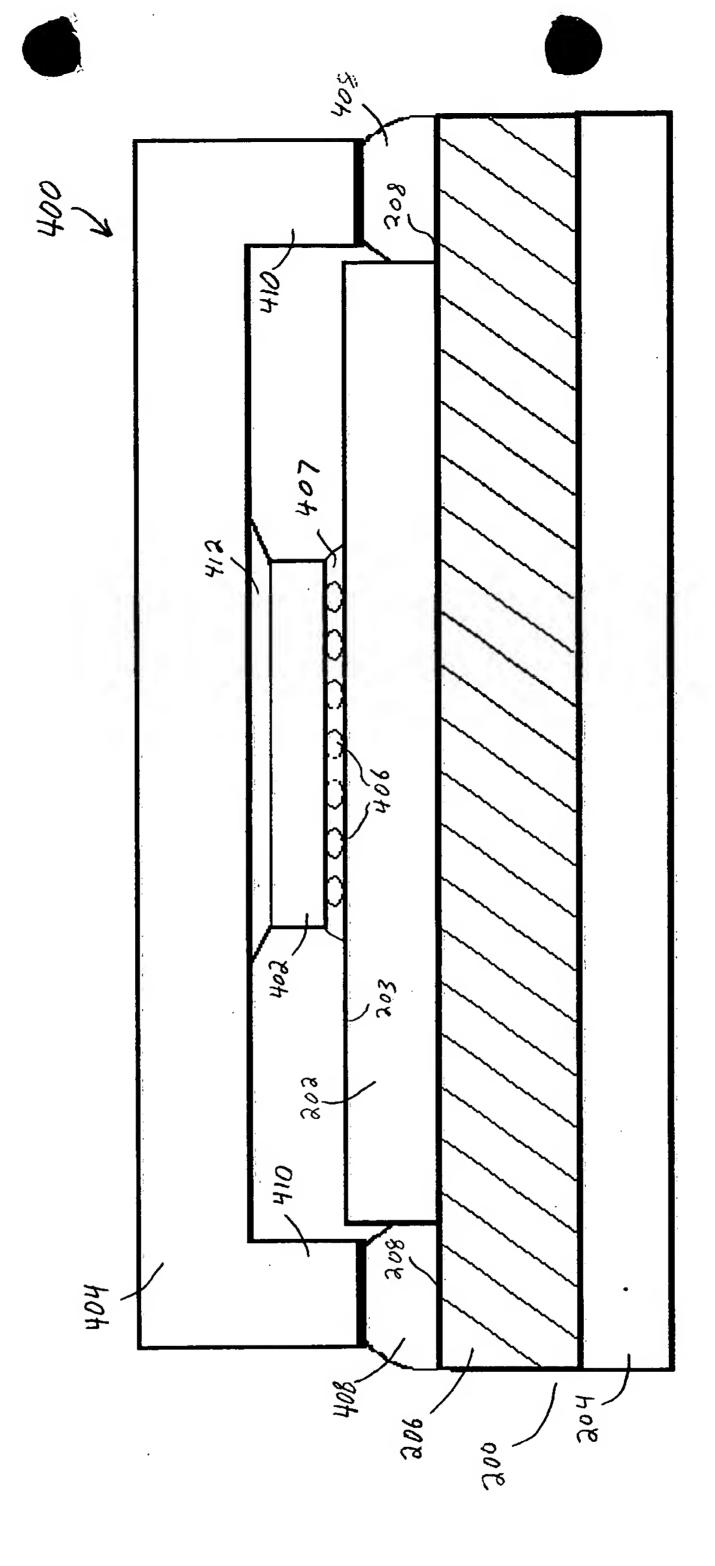
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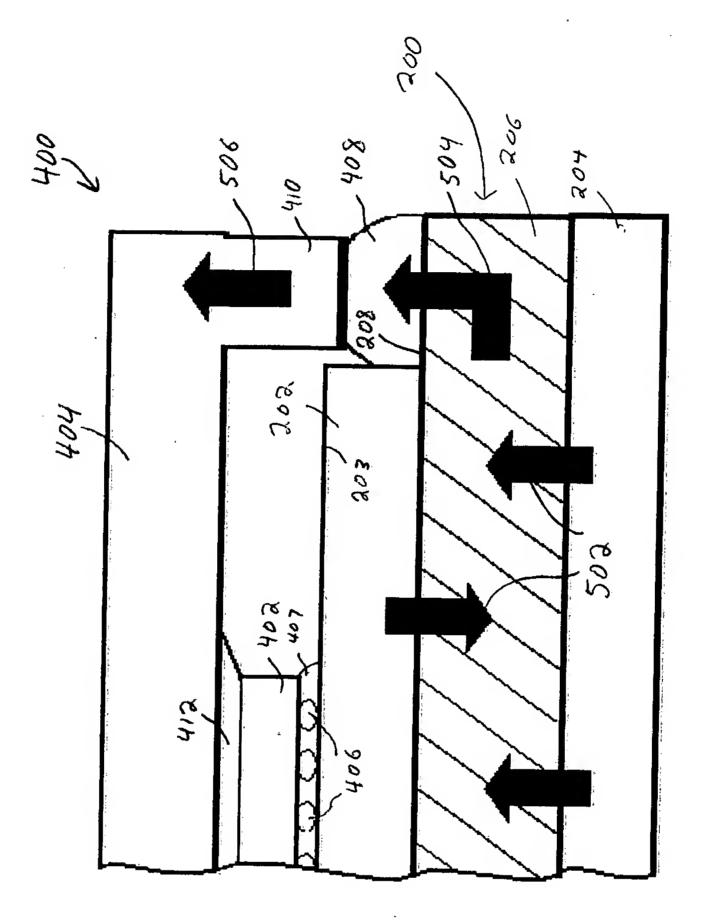


Semiconductor Package with Integrated Heat Spreader Attached to a

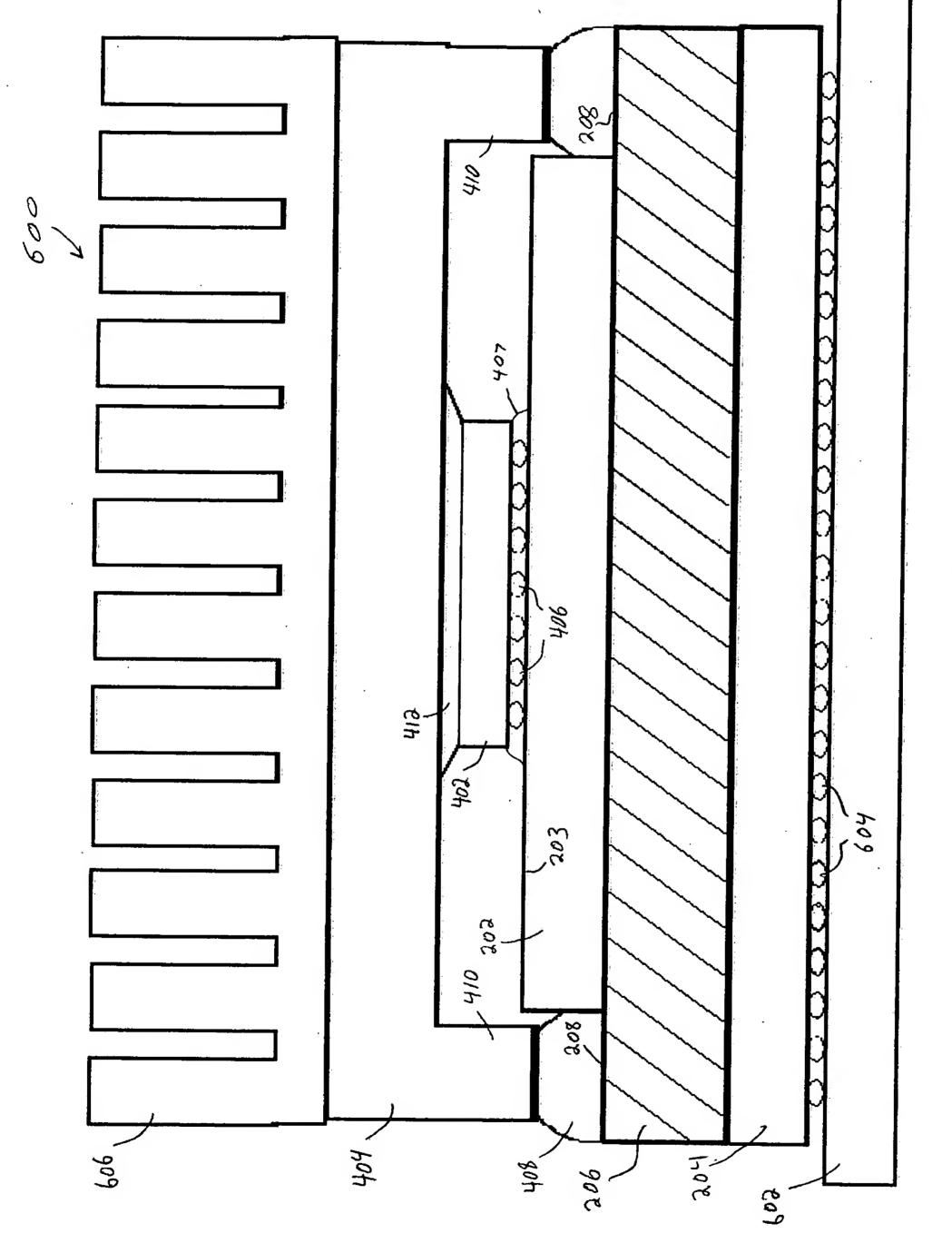
Timothy M. Takeuchi Thermally Conductive Substrate Core

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:eltiT



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Figure

Semiconductor Package with Integrated Heat Spreader Attached to a

Thermally Conductive Substrate Core :əltiT

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